FIG 1

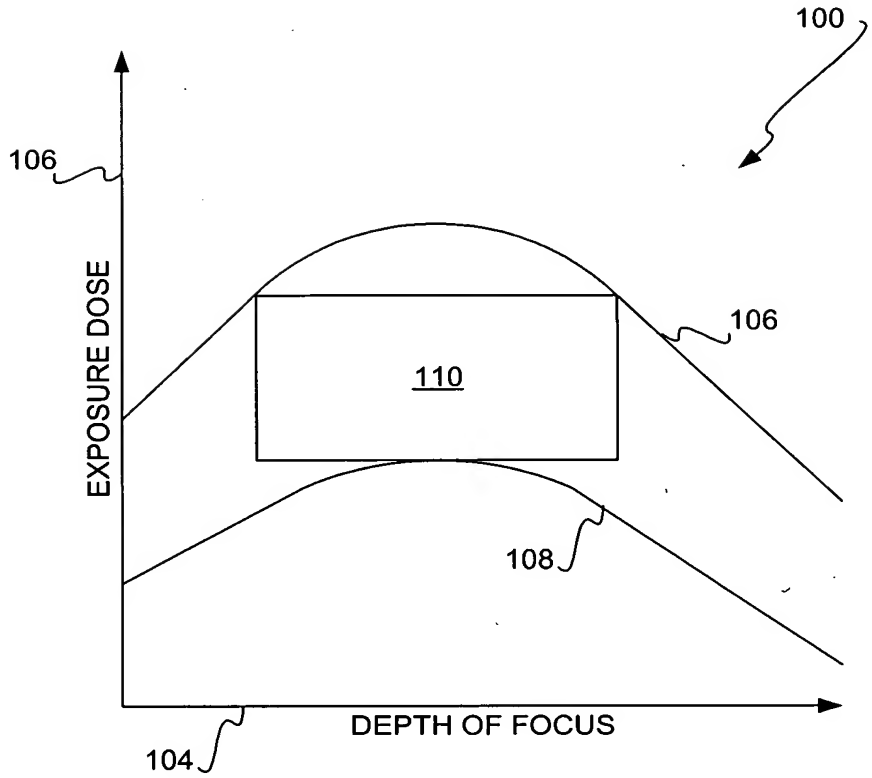


FIG 2

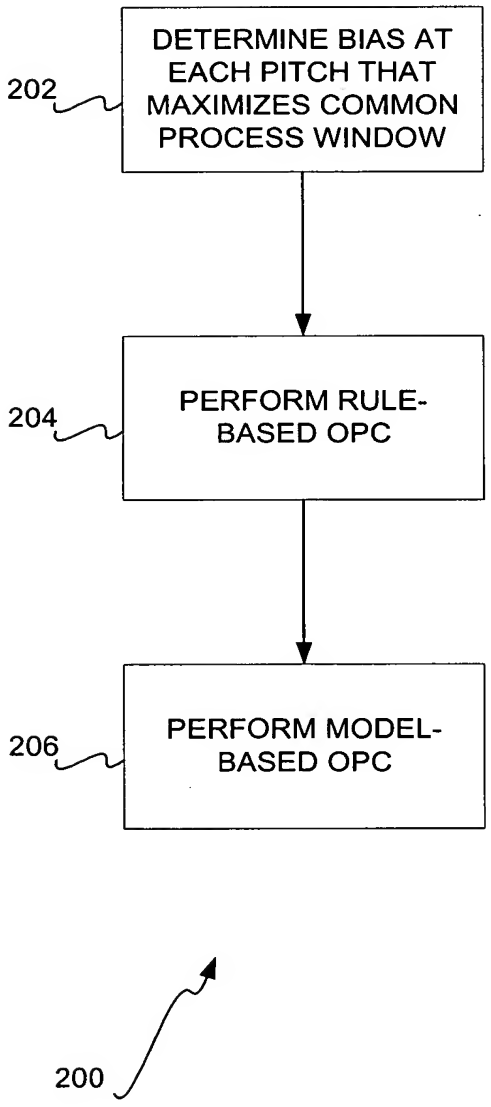

DETERMINE BIAS AT EACH PITCH THAT MAXIMIZES COMMON PROCESS WINDOW
202
PERFORM RULE-BASED OPC
204
PERFORM MODEL-BASED OPC
206
200

FIG 3A

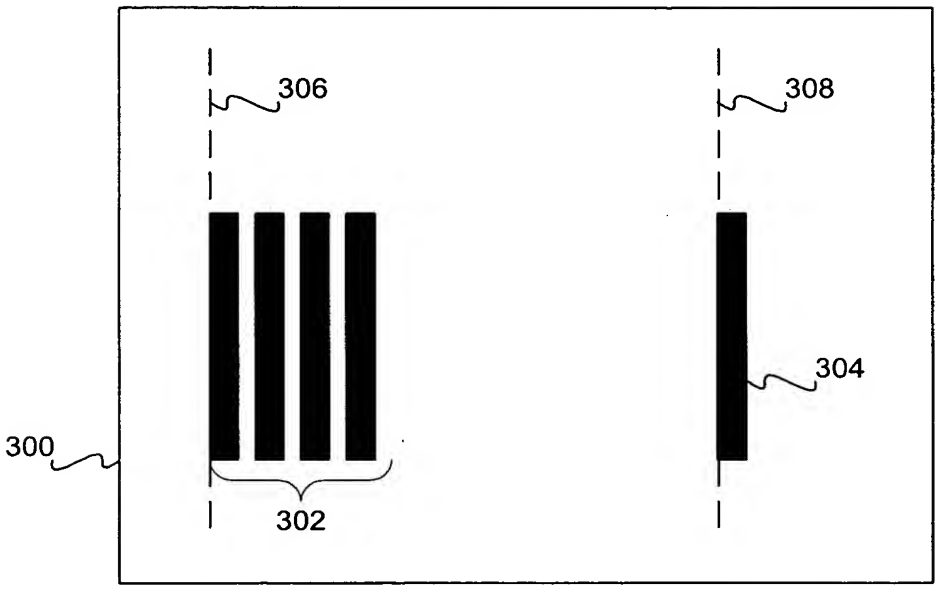


FIG 3B

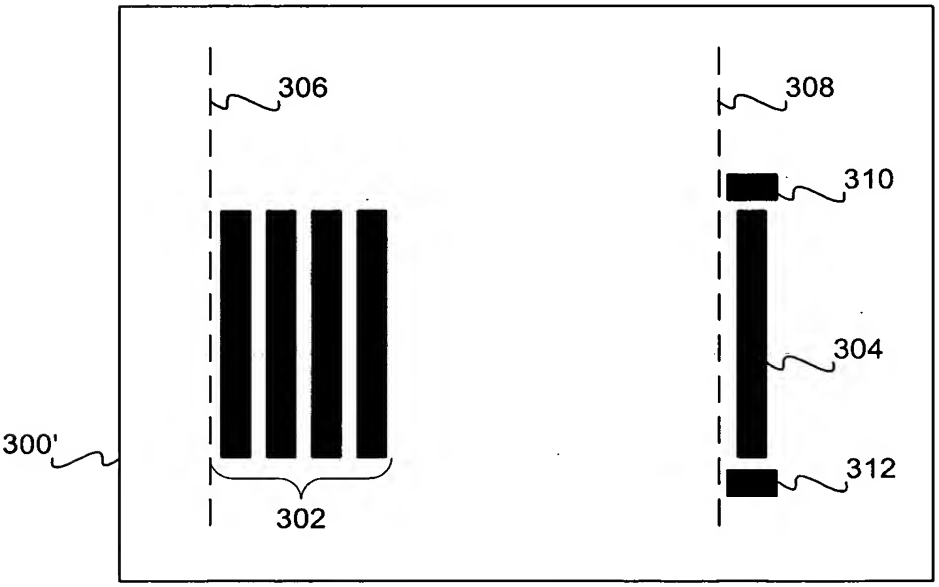


FIG 4

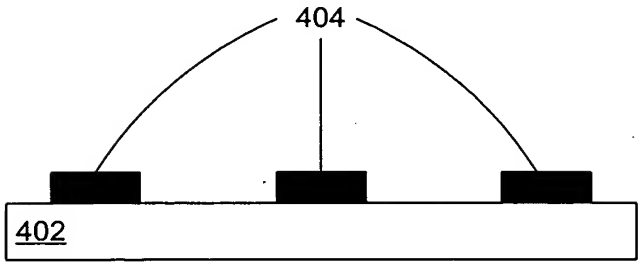


FIG 5

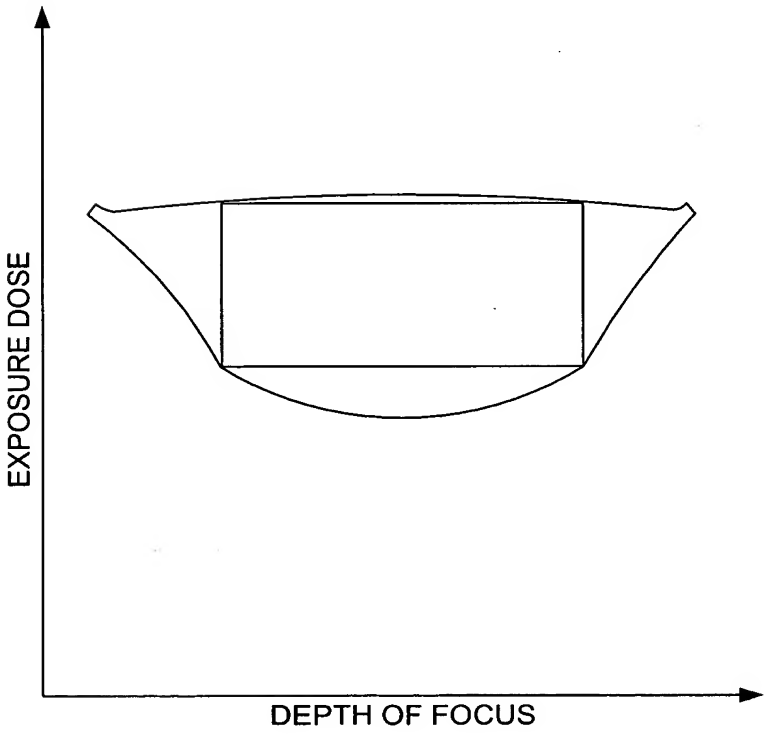


FIG 6

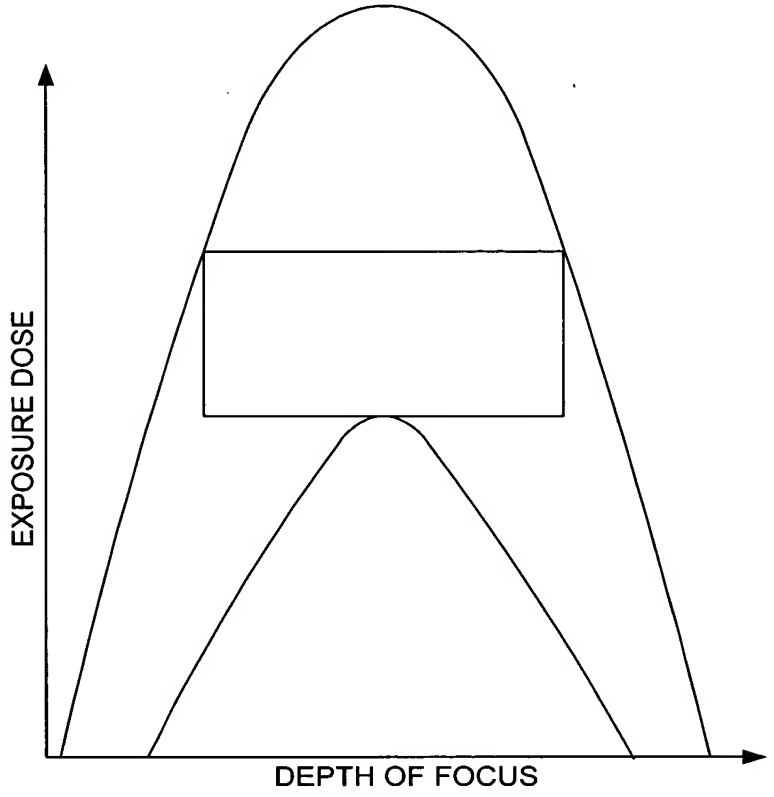


FIG 7

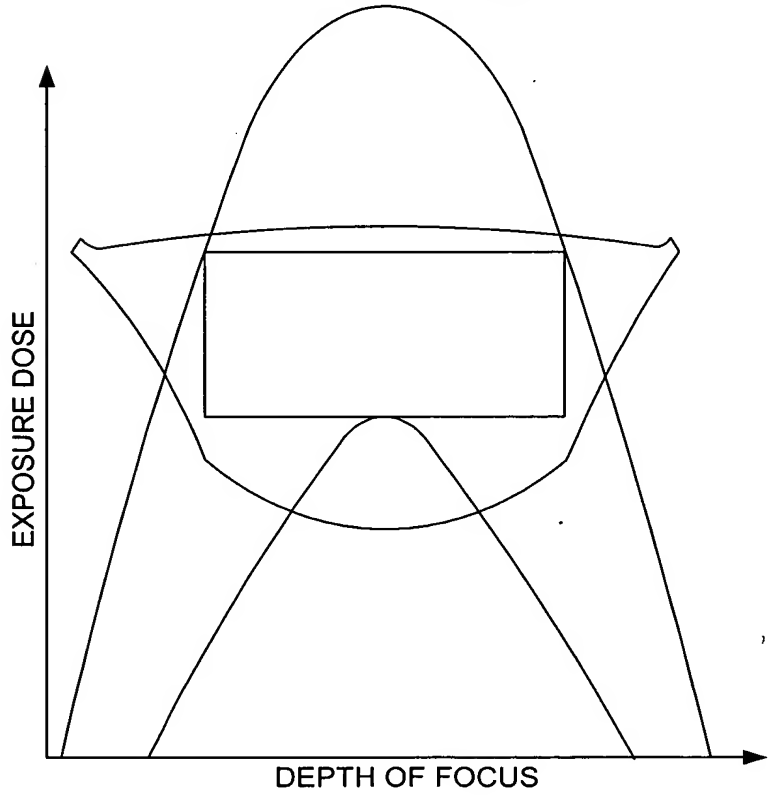


FIG 8

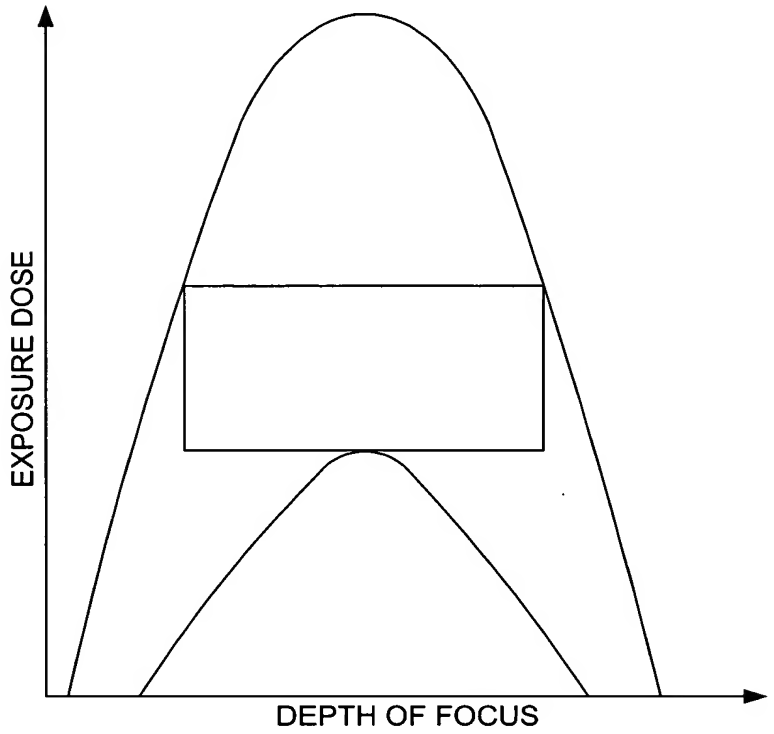


FIG 9

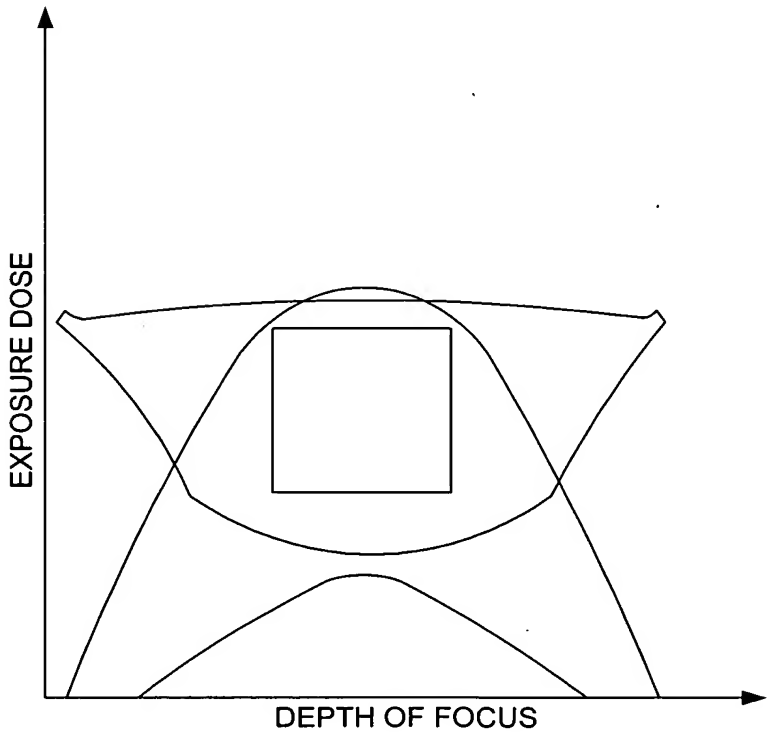
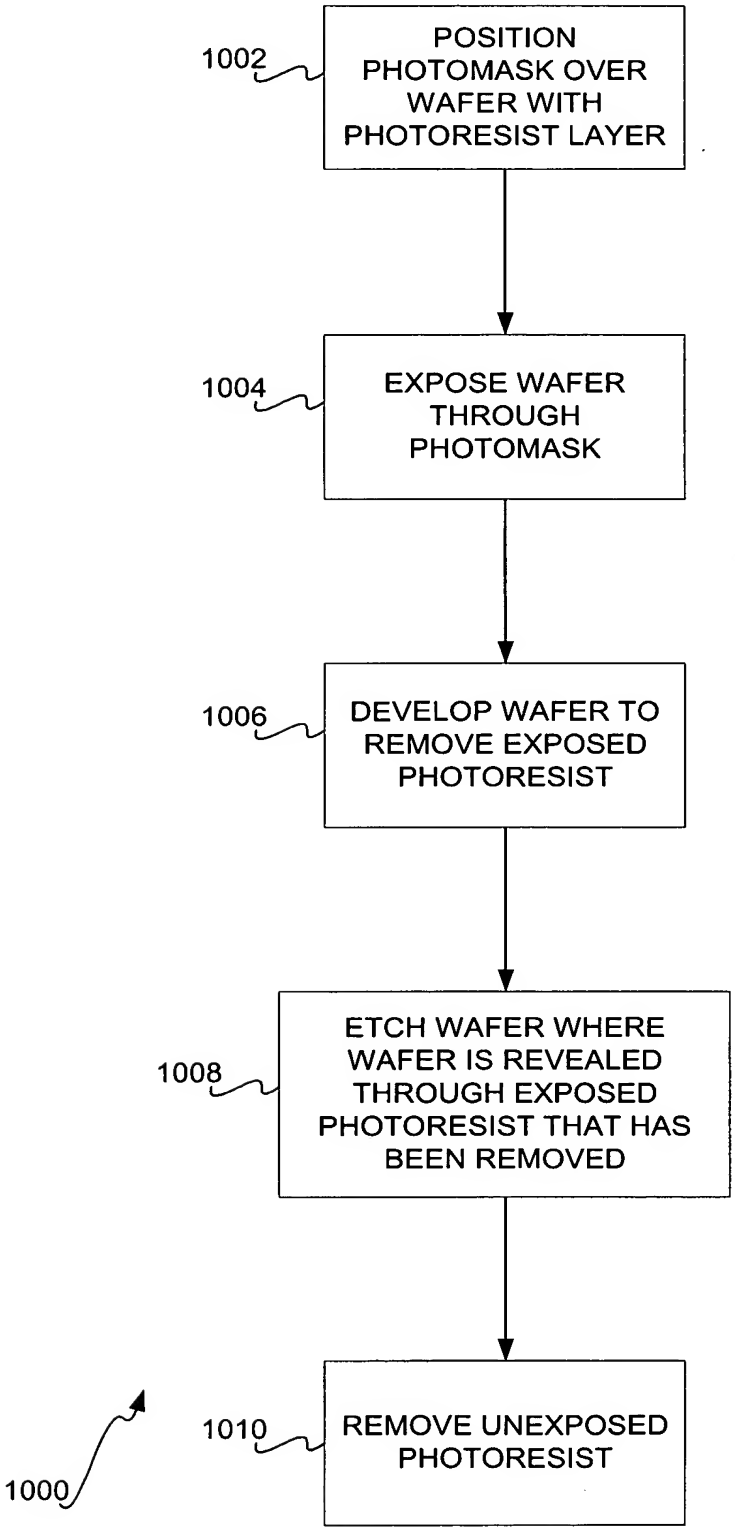


FIG 10


1002
POSITION PHOTOMASK OVER WAFER WITH PHOTORESIST LAYER
1004
EXPOSE WAFER THROUGH PHOTOMASK
1006
DEVELOP WAFER TO REMOVE EXPOSED PHOTORESIST
1008
ETCH WAFER WHERE WAFER IS REVEALED THROUGH EXPOSED PHOTORESIST THAT HAS BEEN REMOVED
1010
REMOVE UNEXPOSED PHOTORESIST
1000